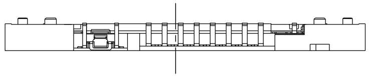
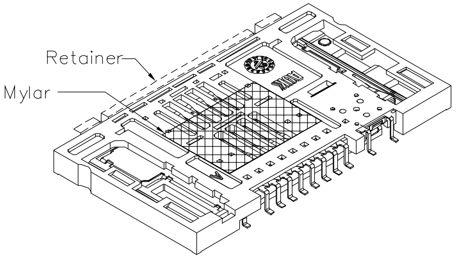
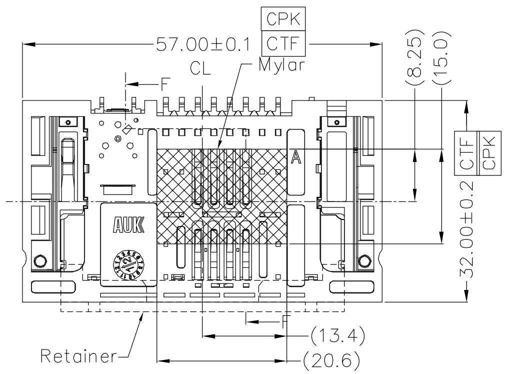
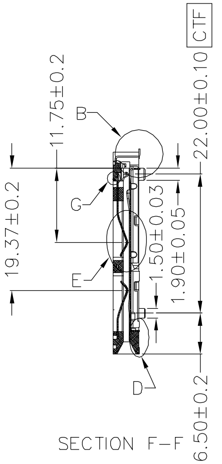
File No.	384-20200401A	SHEET 1/3

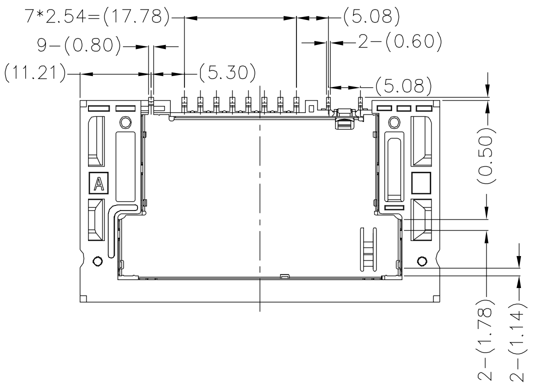


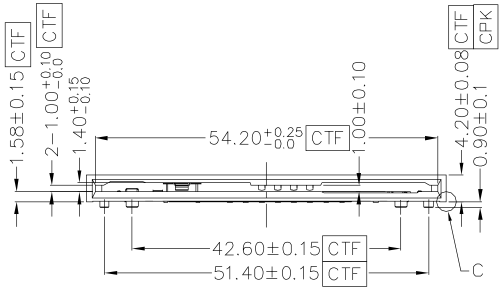


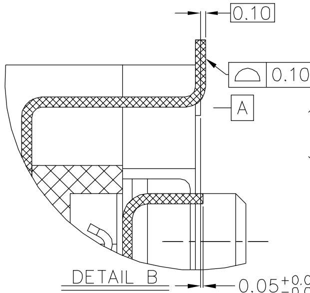




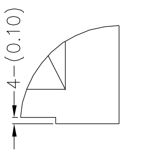
SECTION F-F



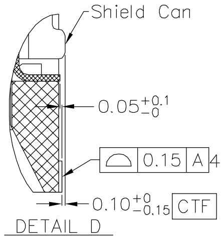




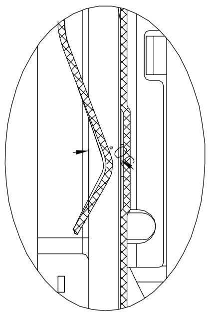
DETAIL B
SCALE 8:1



DETAIL C
SCALE 10:1



DETAIL D
SCALE 5:1



DETAIL E
SCALE 5:1

Specifications:

1. General Information
   . Contact Principle: Friction Technology
   . Mounting Type: SMT
   . Switch: Normal Open With Sealed End Switch
   . Durability: Insert And Withdraw Card For 500,000 Cycles
   At Maximum Rate Of 600 Cycles Per Hours
   (Conditions:In A Clean Office Room.In Damp
   Or Dirty Atmosphere,The Life May Be 1/3
   To 1/5 Of The Above Figures)
   . Material&Finish:
   Data Contact: Copper Alloy (C5210)
   Gold Flash Over Palladium 30u" Over Nickel 80u" Min.
   On Contact Area,Tin 150u" Min. Plated On Terminal Area
   Insulator: LCP UL94V-0
   Switch: Copper Alloy (C2680)
   Gold Flash Over Nickel 80u"Min. Plated On Contact Area,
   Tin 100u"Min. Plated On Terminal Area
   Shielding Can: Stainless Steel (SUS 304)
   Nickel 50u"Min. Plated Overall
2. Electrical Specification
   . Contacts
   Contact Resistance: 200m Ohms Max.
   Insulator Resistance: 1000M Ohms Min.
   Dielectric Withstanding Voltage: 1000V AC R.M.S. Min.(Sea Level)
   Rating Voltage: 30V AC
   Current Rating: 1A Max,10uA Min.
   . Sealed End Switch
   Switching Voltage: 20mV Min. 50V Max.
   Switching Current: 1mA Min. 300mA Max.
   Switching Load: 1VA Max.
   Contact Resistance: 400m Ohms Max.
   Insulation Resistance: 100M Ohms Min.
3. Mechanical Specification
   . Card Insertion Force: 4N Max.
   . Card Withdrawal Force: 0.8N~2.5N(For 0.68~0.84mm and 1.3mm Max. emboss characters height Thickness Card)
   . Contact Force: 0.2N ~ 0.6N
   . Contact Retention Force: 0.3kgf Min.
   . Metal Pin Retention Force: 0.3kgf Min.
4. Environmental Specification
   . Operating Temperature: -40°C ~ +70°C
   . Operating Humidity: 10% ~ 100% RH
   . Solderability: Reflow Soldering: 260°C 10 Sec. Max.
   . Storage Temperature: -40°C ~ +85°C
   . Air Pressure: 70kPa ~ 106kPa.
5. Chip Contact Location Specification
   . According To: ISO 7816-2
   . Contact Style: Ball Radius 0.8mm Min.
6. RoHS Compliant.
7. CTF:Indicates Critical-To-Function Dimension.
   CPK:Indicates CPK Dimension.
8. Retainer Requirements:
   After Reflow Soldering, Please Let Retainer Keep Staying With PSCR
   In Room Temperature(25°C±2°C), 2 Hours At Least Before Pull It Out

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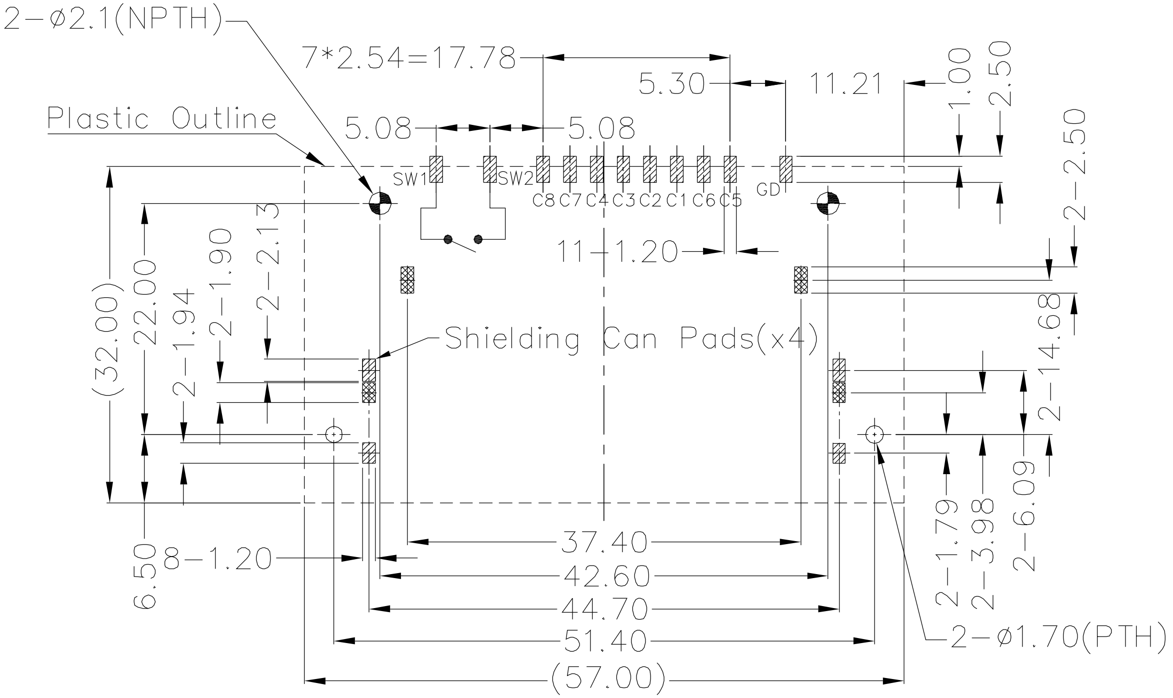
CATEGORY SMART CARD		APPROVED BY CYL	UNLESS OTHERWISE SPECIFIED TOLERANCES ARE
PART No. SCGW08S04020PCNJ13RH		CHECKED BY LYS	.x ±0.38
DRAWING No. SCGW08S04020PCNJ13RH		DRAWING BY SJH	.xx ±0.25 ANG. ±1°
SCALE	NONE	REV. A0	UNIT mm

NO.	REV.	REVISIONS	CHK	DATE
0	A0	NEW RELEASE	SJH	04/01/2020

File No.	384-20200401A	SHEET 2/3



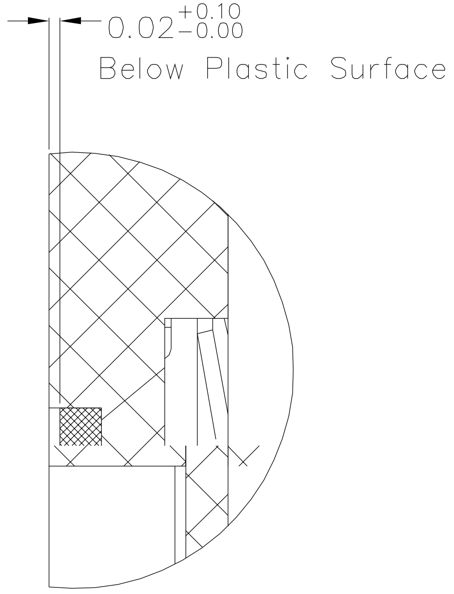
* PTH:Pad Through Hole

* NPTH:No Pad Through Hole

* ▨:Pad Area

* ▩:Keep Out Area(No Solder Paste)

Reference P.C.B. Layout(Tolerance: ±0.05mm)



DETAIL G

SCALE 20:1

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CATEGORY SMART CARD		APPROVED BY CYL	
PART No. SCGW08S04020PCNJ13RH		CHECKED BY LYS	
DRAWING No. SCGW08S04020PCNJ13RH		DRAWING BY SJH	
SCALE	NONE	REV.	A0

UNLESS OTHERWISE SPECIFIED TOLERANCES ARE
.x ±0.38
.xx ±0.25
ANG. ±1°
UNIT mm

NO.	REV.	REVISIONS	CHK	DATE
0	A0	NEW RELEASE	SJH	04/01/2020